

# EMC1833 Evaluation Board User's Guide

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# EMC1833 EVALUATION BOARD USER'S GUIDE

# **Table of Contents**

Preface	. 5
Introduction	. 5
Document Layout	. 5
Conventions Used in this Guide	. 6
Recommended Reading	. 7
The Microchip Website	. 7
Product Change Notification Service	. 7
Customer Support	. 7
Document Revision History	. 7
Chapter 1. Product Overview	
1.1 Introduction	. 9
1.2 EMC1833 Device Overview	. 9
1.3 EMC1833 Evaluation Board Overview	. 9
1.4 Evaluation Board Kit Contents	10
Chapter 2. Installation and Operation	
2.1 Getting Started	11
2.2 System and Configuration Requirements	11
2.3 Board Setup	11
2.4 Software Setup	13
Chapter 3. Software GUI Description	
3.1 Thermal Management Utility Software GUI Overview	17
3.2 Real-Time Acquisition Action Buttons	18
3.3 Temperatures, Sensor Settings and Registers List tabs	19
3.4 Data Acquisition Charting Area	23
Appendix A. Schematic and Layouts	20
A.1 Introduction	3U 21
A.2  ADM00773 Board = Schematic  2	21 22
A 4 Board – Top Silk	33
A.5 Board – Top Copper and Silk	33
A.6 Board – Top Copper	34
A.7 Board – Bottom Copper	34
A.8 Board – Bottom Copper and Silk	35
A.9 Board – Bottom silk	35
Appendix B. Bill of Materials (BOM)	36

Worldwide Sales and Service	
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# EMC1833 EVALUATION BOARD USER'S GUIDE

### Preface

### NOTICE TO CUSTOMERS

All documentation becomes dated, and this manual is no exception. Microchip tools and documentation are constantly evolving to meet customer needs, so some actual dialogs and/or tool descriptions may differ from those in this document. Please refer to our website (www.microchip.com) to obtain the latest documentation available.

Documents are identified with a "DS" number. This number is located on the bottom of each page, in front of the page number. The numbering convention for the DS number is "DSXXXXXXA", where "XXXXXXX" is the document number and "A" is the revision level of the document.

For the most up-to-date information on development tools, see the MPLAB<sup>®</sup> IDE online help. Select the Help menu, and then Topics to open a list of available online help files.

#### INTRODUCTION

This chapter contains general information that will be useful to know before using the EMC1833 Evaluation Board User's Guide. Items discussed in this chapter include:

- Document Layout
- Conventions Used in this Guide
- Recommended Reading
- The Microchip Website
- Product Change Notification Service
- Customer Support
- Document Revision History

#### **DOCUMENT LAYOUT**

This document describes how to use the EMC1833 Evaluation Board User's Guide as a development tool to emulate and debug firmware on a target board. The manual layout is as follows:

- **Chapter 1. "Product Overview"** Important information about the EMC1833 Evaluation Board User's Guide.
- Chapter 2. "Installation and Operation" This chapter includes a detailed description of each function of the evaluation board and instructions on how to use the board.
- Chapter 3. "Software GUI Description" Includes instructions to evaluate the EMC1833 for temperature sensing applications.
- Appendix A. "Schematic and Layouts" Shows the schematic and layout diagrams for the EMC1833 Evaluation Board User's Guide.
- Appendix B. "Bill of Materials (BOM)" Lists the parts used to build the EMC1833 Evaluation Board User's Guide.

### CONVENTIONS USED IN THIS GUIDE

This manual uses the following documentation conventions:

#### **DOCUMENTATION CONVENTIONS**

Description	Represents	Examples
Arial font:		
Italic characters	Referenced books	MPLAB <sup>®</sup> IDE User's Guide
	Emphasized text	is the only compiler
Initial caps	A window	the Output window
	A dialog	the Settings dialog
	A menu selection	select Enable Programmer
Quotes	A field name in a window or dialog	"Save project before build"
Underlined, italic text with right angle bracket	A menu path	<u>File&gt;Save</u>
Bold characters	A dialog button	Click OK
	A tab	Click the <b>Power</b> tab
N'Rnnnn	A number in verilog format, where N is the total number of digits, R is the radix and n is a digit.	4'b0010, 2'hF1
Text in angle brackets < >	A key on the keyboard	Press <enter>, <f1></f1></enter>
Courier New font:		
Plain Courier New	Sample source code	#define START
	Filenames	autoexec.bat
	File paths	c:\mcc18\h
	Keywords	_asm, _endasm, static
	Command-line options	-0pa+, -0pa-
	Bit values	0, 1
	Constants	0xFF, `A'
Italic Courier New	A variable argument	<i>file.o</i> , where <i>file</i> can be any valid filename
Square brackets [ ]	Optional arguments	mcc18 [options] file [options]
Curly brackets and pipe character: {   }	Choice of mutually exclusive arguments; an OR selection	errorlevel {0 1}
Ellipses	Replaces repeated text	<pre>var_name [, var_name]</pre>
	Represents code supplied by user	<pre>void main (void) { }</pre>

#### **RECOMMENDED READING**

This user's guide describes how to use the EMC1833 Evaluation Board. Other useful documents are listed below. The following Microchip documents are available and recommended as supplemental reference resources:

EMC1812/13/14/15/33 Data Sheet – *"EMC1812/13/14/15/33 DS Multi-Channel Low-Voltage Remote Diode Sensor Family Data Sheet"* (DS20005751).

PIC18(L)F2X/45K50 Data Sheet – "28/40/44-Pin, Low-Power, High-Performance Microcontrollers with XLP Technology" (DS30000684).

#### THE MICROCHIP WEBSITE

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- **Product Support** Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip consultant program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

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- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

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Technical support is available through the website at: http://www.microchip.com/support

#### DOCUMENT REVISION HISTORY

#### **Revision A (February 2018)**

· Initial release of this document.

NOTES:



# EMC1833 EVALUATION BOARD USER'S GUIDE

# **Chapter 1. Product Overview**

### 1.1 INTRODUCTION

This chapter provides an overview of the EMC1833 Evaluation Board:

- What is the EMC1833 Device?
- What is the EMC1833 Evaluation Board?
- What the EMC1833 Evaluation Board Kit Contains

#### 1.2 EMC1833 DEVICE OVERVIEW

The EMC1833 Evaluation Board is used to evaluate the EMC18XX family of remote diode temperature monitors. Users can now easily evaluate many of the integrated features of the EMC18XX device family. The device also has a on-board connector configured for an anti-parallel diode to allow for off-board temperature measurements. In addition, the evaluation board connects to PC through a USB interface. Temperature can be data-logged using the Microchip Thermal Management Software Graphical User Interface (GUI).

#### 1.3 EMC1833 EVALUATION BOARD OVERVIEW

The board enables users to easily evaluate many custom programmable features such as Rate of Change, Temperature Alert Limit settings, Temperature Conversion Rate, Resistance Error Correction (REC) and Power Modes.

Figure 1-1 shows the top view of the EMC1833 Evaluation Board.



FIGURE 1-1: EMC1833 Evaluation Board (ADM00773) - Top View.



Figure 1-2 shows the bottom view of the EMC1833 Evaluation Board.

FIGURE 1-2: EMC1833 Evaluation Board (ADM00773) - Bottom View.

### 1.4 EVALUATION BOARD KIT CONTENTS

The EMC1833 Evaluation Board Kit includes:

- EMC1833 Evaluation Board (ADM00773)
- USB cable
- 2N3904FS-ND transistor (TO-92 package)
- Important Information Sheet



### EMC1833 EVALUATION BOARD USER'S GUIDE

# **Chapter 2. Installation and Operation**

#### 2.1 GETTING STARTED

This section describes how to power-up and interface with the EMC1833 Evaluation Board. Items discussed in this chapter include:

- · System and configuration requirements
- The hardware setup required prior to using the evaluation board
- · Performing software setup
- Operating the device's software interface, the Thermal Management Utility [EMC1833] GUI.

#### 2.2 SYSTEM AND CONFIGURATION REQUIREMENTS

The EMC1833 Evaluation Board is designed to be used in a Microsoft<sup>®</sup> Windows<sup>®</sup> XP<sup>®</sup> (SP3 or later) environment, based on the Microsoft.NETTM Framework 2. Users can utilize the Microsoft .NET Framework 2 web installer package to download and install the .NET Framework components. For USB connectivity, the minimal physical requirement for the PC is a standard USB 2.0 port. In case the board connects to the PC through a USB hub, use a self-powered hub.

#### 2.3 BOARD SETUP

Before the EMC1833 Evaluation Board can be used, a few steps must be performed to install the PC software and configure the board's hardware.

- 1. Download the support material (PC application) that can be found on the ADM00773 board page, at www.microchip.com. Unzip the archive and install the .exe file.
- 2. Connect the collector and base of the transistor to the DP input and the emitter to the DN input. The orientation of the transistor is shown below. Note the transistor is flat side down, as you can observe in Figure 2-1.



FIGURE 2-1:



#### 2.3.1 Hardware Setup and Description

Follow these steps to set up the hardware:

- 1. The board has a mini-USB connector for a PC interface. Connect the USB cable from the evaluation board to a PC.
- 2. Start the Thermal Management Software GUI for temperature data logging or to evaluate the sensor board features.

This evaluation board is fully powered from PC USB source, 5V. Once power is applied via USB, and the USB is successfully enumerated then the PIC<sup>®</sup> microcontroller is ready to receive commands from the host PC to program the EMC1833 settings or transfer temperature data.



FIGURE 2-2: EMC1833 Evaluation Board Circuit Block Diagram.

The block diagram in Figure 2-2 shows that the EMC1833 device is able to monitor and report the ambient temperature of two external diode-connected transistors. One diode is installed on the PCB. A two-pin connector allows the user to connect an additional transistor for evaluation of off-board temperature applications. The Alert outputs, SDA, SCK, and VDD are connected to test points for external connections; in addition, these outputs are also connected to the microcontroller I/O pins so that the Alert Output statuses can be detected in software.

#### 2.4 SOFTWARE SETUP

Follow the installation procedure illustrated below:

1. Open the Thermal Management Utility v1.5.5.exe then click Next in the Application Install window.

👺 Thermal M	anagement Utility v1.5.5 Setup
₽	Application Install
Ŭ	Welcome to the Setup Wizard for the Thermal Management Utility.
2	
	< Back Next > Cancel

FIGURE 2-3: Application Install Dialog Box.

2. Read and Accept the License Agreement and click Next.

License Agreement		<u> </u>
Diagon road the following Li	iconco Agroamant Vau a	aust account the
terms of this agreement be	fore continuing with the	installation.
terme er tille egreennent se	iere containing that the	
MICROCHIP SOFTWARE NOTICE #	AND DISCLAIMER:	4
MICROCHIP SOFTWARE NOTICE 2 You may use this software,	AND DISCLAIMER: and any derivatives cre	eated by any
MICROCHIP SOFTWARE NOTICE You may use this software, person or entity by or on y products. Microchip and it	AND DISCLAIMER: and any derivatives cre your behalf, exclusively s licensors retain all	eated by any y with Microchips ownership and
MICROCHIP SOFTWARE NOTICE You may use this software, person or entity by or on y products. Microchip and it intellectual property right all derivatives hereto.	AND DISCLAIMER: and any derivatives cre your behalf, exclusively is licensors retain all is in the accompanying s	eated by any y with Microchips ownership and software and in
MICROCHIP SOFTWARE NOTICE You may use this software, person or entity by or on y products. Microchip and it intellectual property right all derivatives hereto.	AND DISCLAIMER: and any derivatives cre your behalf, exclusively is licensors retain all is in the accompanying s I accept the agreen	with Microchips ownership and software and in
MICROCHIP SOFTWARE NOTICE 2 You may use this software, person or entity by or on y products. Microchip and it intellectual property right all derivatives hereto. Do you accept this license?	AND DISCLAIMER: and any derivatives cre your behalf, exclusively is licensors retain all is in the accompanying s I accept the agreen	with Microchips ownership and software and in nent agreement
MICROCHIP SOFTWARE NOTICE 2 You may use this software, person or entity by or on y products. Microchip and it intellectual property right all derivatives hereto. Do you accept this license? BitBock Installer	AND DISCLAIMER: and any derivatives cre your behalf, exclusively is licensors retain all is in the accompanying s I accept the agreen I do not accept the	eated by any y with Microchips ownership and software and in nent agreement

FIGURE 2-4: License Agreement Dialog Box.

3. Select an installation directory and click **Next**.

🚰 Thermal Manageme	nt Utility v1.5.5 Setup	
Installation Directory		
Please specify the dire be installed.	ctory where the Thermal Ma	nagement Utility will
Installation Directory	C:\Program Files (x86)\Micr	ochip\ThermalManac
BitRock Installer	< Back Nex	t > Cancel

FIGURE 2-5: Installation Directory Dialog Box.

4. Select **Next** to continue with the installation process.

F Thermal Management Utility v1.5.5 Setup	
Ready to Install	<u> </u>
Setup is now ready to begin installing the Thermal on your computer.	Management Utility
BitRock Installer	tt > Cancel

FIGURE 2-6:

Ready to Install Dialog Box.

5. In the **Install Complete** dialog box click **Finish** to finalize installation.



FIGURE 2-7: Install Complete Dialog Box.

NOTES:



### EMC1833 EVALUATION BOARD USER'S GUIDE

# **Chapter 3. Software GUI Description**

### 3.1 THERMAL MANAGEMENT UTILITY SOFTWARE GUI OVERVIEW

The Microchip Thermal Management Software GUI allows users to evaluate the EMC1833 for temperature sensing applications. Once the hardware is connected, the software recognizes the device ID and displays the corresponding GUI for the evaluation board. Disconnecting the USB will close the GUI. This tool enables users to evaluate the sensor features and perform temperature data-log. Figure 3-1 depicts the Thermal Management Utility GUI.



FIGURE 3-1:

Thermal Management Utility GUI.

As displayed in Figure 3-1, the GUI can be divided into three sections:

- 1. One Shot action buttons
- 2. Temperatures, Sensor Settings and Registers List tabs
- 3. Data Acquisition Charting area

#### 3.2 REAL-TIME ACQUISITION ACTION BUTTONS

The **Play**, **Stop**, and **Reset** icons (Figure 3-2) can be used to perform continuous data acquisitions.





To initiate data logging, click the **Record Acquisitions** button. The system displays the Save As window (see Figure 3-3), where users need to select a file name and a location, then click the **Save** button.

Save As					×
💬 💬 – 📜 « Mie	crochip Technology Inc 🕨 Thermal Management	Utility 🕨 1.5.4.0	✓  Searce	h 1.5.4.0	Q
Organize 🔹 Nev	v folder				0
★ Favorites	Name	Date modified	Туре	Size	
🗼 Downloads 🐉 Recent Place	No	items match your search.			
Libraries Documents					
A Music					
Subversion					
JUDE Videos					
🛸 Computer 👻					
File name:	temp				•
Save as type:	Data File (*.txt)				•
<ul> <li>Hide Folders</li> </ul>			Save	Cancel	

#### FIGURE 3-3:

Save As Window for Recording Acquisitions.

To stop the data logging click the **Stop Recording** button. Users can now go to the file location to view the file.

#### 3.3 TEMPERATURES, SENSOR SETTINGS AND REGISTERS LIST TABS

#### 3.3.1 Temperatures Tab

The **Temperatures** tab displayed in Figure 3-4 shows the results of the Internal Diode 1 and Diode 2 sensors. This tab also displays the result of the various user programmable features of the EMC1833, such as the temperature ALERT and THERM status, Diode Fault status, the Rate of Change (ROC), and hottest diode comparison.



FIGURE 3-4:

Temperatures Tab.

#### 3.3.2 Sensor Settings Tab

The Sensor Settings tab is divided into two sections:

- General Settings
- Rate of Change

Figure 3-5 displays the **General Settings** section under the **Sensor Settings** tab. This is where the user configures and enables/disables various features of the device.

Refer to the MCP1812/13/14/15/33 data sheet for detailed information on the operation of these features and settings.

	Temperatures	Sensor Settings	Registers List	
			Rate of Ch	ange General Settings
	Sensor Se	ttings		
Select or clear the check boxes to enable and disable features Temperature hysteresis value for ALERT and THERM	Dynam CREC D Anti Pa Therm Hys 10	ic Averaging On 1/D2 On rallel Diode On steresis	Active Mode Range (C) Consecutive Alert Consecutive Therm	Run     ▼       0127.875     ▼       1     ▼       4     ▼
Select or clear the check boxes to enable and disable features Temperature hysteresis value for ALERT and THERM ALERT limits Set output type as comparator or interrupt Mask the alert signal for all temperature channels and ROC events Mask the alert signal for specific temperature channels	CLimit Set	ttings (C)	Conversion Rate	4
		Internal	Ext 1	Ext 2
	High	85	85	85
ALERT limits	Low	0	0	0
	Therm	85	85	85
Set output type as comparator or interrupt Mask the alert signal for all temperature channels and ROC events Mask the alert signal for specific temperature channels	Alerts Alert Pi	in Mode Interrup sk All Ma	ot  v  sk Individual Settings Internal Diode External Diode 1 External Diode 2	ROC 1

FIGURE 3-5:

Sensor Settings Tab - General Settings.

Figure 3-6 displays the **Rate of Change** (ROC) section under the **Sensor Settings** tab. This is where the user configures the ROC feature. Refer to the MCP1812/13/14/15/33 data sheet for detailed information regarding the ROC setup and operation.

I emperature Rate of	Change Settings
Enable ROC	Hysteresis (C) 0
	Channel 1
Gain	1
Samples	2
Limit (C)	0

FIGURE 3-6: Rate of Change Tab.

Since the software is constantly polling the status register the status bits are cleared as soon as an out of bounds condition is satisfied when in the Interrupt mode.

A quick way to validate the ROC is utilizing the Standby mode along with the one-shot temperature measurement.

ROC validation example:

- 1. Select Standby mode.
- 2. Set the Gain and Samples drop downs.
- 3. Select the **Enable ROC** check box.
- 4. Click one-shot.
- 5. Update registers and log temperature for Remote Diode 1.
- 6. Repeat steps 4 and 5 for the samples selected (when all samples have completed the ROC result value will update).
- 7. Calculate the ROC result using Equation 3-1 and compare to the calculated value in the ROC result within the GUI.

#### **EQUATION 3-1:**

		$\frac{\Delta T}{\Delta t} = \frac{[T(t_{max}) - T(t_0)] \notin gain}{(sample - 1)}$
Where:		
T(T <sub>Tmax</sub> ) T(t <sub>0</sub> )	= =	Temperature at the end of the interval. Temperature at the beginning of the interval.

### 3.3.3 Registers List Tab

The **Registers List** tab (Figure 3-7) contains a read-only table that contains all the user registers.

Name	Address High	Address Low	Data High	Data Low	*
Ext1 Temp	0x01	0×10	0x16	0xC0	
Status	-	0x02	-	0x00	
Config	-	0x03	-	0x00	
Convert	-	0x04	-	0x06	
Internal Diode High Limit	-	0x05	-	0x55	
Internal Diode Low Limit	-	0x06	-	0x00	
Ext1 High Limit	0x07	0x13	0x55	0x00	
Ext1 Low Limit	0×08	0x14	0x00	0x00	=
One Shot	-	0x0F	-	0x00	-
Scratchpad1	-	0x11	-	0x00	
Scratchpad2	-	0x12	-	0x00	
Ext2 High Limit	0×15	0x17	0x55	0x00	
Ext2 Low Limit	0×16	0×18	0x00	0x00	
Ext1 Therm Limit	-	0×19	-	0x55	
Ext2 Therm Limit	-	0x1A	-	0x55	
Ext Diode Fault Status	-	0×1B	-	0x00	
Ext Diode Fault Mask	-	0x1F	-	0x00	
Internal Therm Limit	-	0x20	-	0x55	
Therm Hysteresis	-	0x21	-	0x0A	
Consecutive Alert	-	0x22	-	0x70	
Ext2 Temp	0x23	0x24	0x16	0x80	
Ext1 Ideality	-	0x27	-	0x12	
Ext2 Ideality	-	0x28	-	0x12	
High Limit Status	-	0x3A	-	0x00	
Low Limit Status	-	0x3B	-	0x00	

FIGURE 3-7:

Registers List Tab.

### 3.4 DATA ACQUISITION CHARTING AREA

Figure 3-8 shows the data acquisition interface with a plot of the EMC1833 Internal Diode, Diode 1 and Diode 2.



FIGURE 3-8:

Microchip Thermal Management Sensor GUI Data Plot.

The logging interval can be adjusted using the interval scroll bar from 100ms to 30s, as shown in Figure 3-8.

The data acquisition charting area (Figure 3-8) can be customized by double clicking the chart. Performing this action opens the Data Acquisition Customization window, available in Figure 3-9.

Users can also zoom into a specific plot range by clicking and dragging the section. The data in the chart can also be exported using the **Export** button.

# **EMC1833 Evaluation Board User's Guide**

Data Acquisition Customization	
General     Plot     Subsets     Points       Main Title:     Data Acquisition       Sub Title:	Axis Font Color Style
Border Style No Border Cline Shadow 3D Inset	Numeric Precision © 0
Viewing Style ● Color ● Monochrome ● Monochrome + Symbols	Grid Lines ● Both ○ Y ○ X ○ None ☑ Grid in front of data Display
Font Size	⊚ Graph
OK Cancel Apply	Help Export Maximize
	راً Export Data



#### 3.4.0.1 DATA ACQUISITION CUSTOMIZATION WINDOW DESCRIPTION

The Data Acquisition Customization window contains eight tabs which contain different options allowing users to customize the data acquisition charting area.

The **General** tab (Figure 3-9) determines how the data acquisition charting area is displayed. General options include the border style, viewing style, font size, numeric precision and grid lines.

The **Display** option determines how the data acquisition charting area is generated: a graph, a table, or both.

Data Acquisition Customization		
General       Plot       Subsets       Points       As         All Subsets       Internal Temp       Ext1 Temp       Ext2 Temp       Ext2 Temp         Sb       Off       Shadow       Image: Shadow <td< td=""><td>Area Bar Line Points-BestFitCurve Points+BestFitCurve II Points+BestFitLine II Points+Line Points+Line Points+Spline Spline</td><td></td></td<>	Area Bar Line Points-BestFitCurve Points+BestFitCurve II Points+BestFitLine II Points+Line Points+Line Points+Spline Spline	
OK Cancel	Apply	Export Maximize

The **Plot** tab, displayed in Figure 3-10, allows users to customize the appearance of the data sensor plots.

FIGURE 3-10: Data Acquisition Customization - Plot Tab.

Users can also control the appearance of the subsets plots using the **Subsets** tab, displayed in Figure 3-11.

Data Acquisition Customization		
General Plot Subsets Points Axis	Font Color Style	
Subsets to Graph		
Internal Temp Ext1 Temp	Scrolling Subsets	
Ext2 Temp		
OK Cancel	Apply Export.	Maximize

FIGURE 3-11:

Data Acquisition Window - Subsets Tab.

The **Points** tab, displayed in Figure 3-12, controls the number of data points displayed in the graph and the orientation of the labels on the X-Axis.

Data Acquisition Customiz	ation					
General Plot Subsets	Points	Axis	Font	Color	Style	
Points to Graph Sequential 100 ( III )	0 1 2 3 4 5 6 7 8 9 10 11 12 13 14	Sele	ected			Point Label Orientation Auto Vertical Horizontal Slanted
OK Cano	el	Ap	ply			Export Maximize

#### FIGURE 3-12: Data Acquisition Window - Points Tab.

The **Axis** tab, displayed in Figure 3-13, determines the scale and range of the Y-Axis.

eneral Plot	Subsets Points Axis	Font Color Style	
Y Axis			
Linear	<ul> <li>Auto</li> </ul>		
─ Log	C Min		
_	Max		
	Min/Max		
Min	Max		
-40.0000	100		

FIGURE 3-13:

Data Acquisition Window - Axis Tab.

Users can modify the options in the **Font** tab, displayed in Figure 3-14, to change the size, font and style of the text that appears in the data acquisition charting area. A sample text is also provided for preview before applying the changes to the charting area.

Data Acquisition Customization			
General Plot Subsets Points Axis	Font	Color Style	
Main Title:			
Times New Roman 🔻	bold	italic u	nderline
Sub-Title:			
Times New Roman 🗸	📃 🔲 bold	italic u	nderline
Subset/Point/Axis Labels:			
Arial Baltic 🗸	🛛 🔽 bold	🔲 italic 🛛 🔽 ur	nderline
Table Data:			
Arial	]		
	)dEe	FfGa	
OK Cancel	Apply		Export Maximize

#### FIGURE 3-14: Data Acquisition Window - Font Tab.

The **Color** tab, displayed in Figure 3-15, determines which colors are used by the system. Optionally, users can select a preconfigured style in the Quick Styles section.

Data Acquisition Customization				
General       Plot       Subsets       Points       Axis       Free         Graph Attributes <ul> <li>Desk Foreground</li> <li>Desk Background</li> <li>Shadow Color</li> <li>Graph Foreground</li> <li>Graph Background</li> <li>Table Foreground</li> <li>Table Background</li> </ul> Table Background	Ont Color Style	dient Styles Medium Inset Shadow Line No Border	Dark Olinset Shadow Line No Border	
OK Cancel Apply	/		Export	Maximize



Data Acquisition Window - Color Tab.

Through the **Style** tab, displayed in Figure 3-16, users can customize the line style, color, and data point type for each temperature plot.

General	Plot	Subsets	Points	Axis	Font	Color	Style
0				_			
Ext1 Te	Temp						
Ext2 Te	mp						
							puncture attent
							Point Type:
							●Solid Circle
							Line Type:
							<b>_</b>

FIGURE 3-16: Data Acquisition Window - Style Tab.

NOTES:



# EMC1833 EVALUATION BOARD USER'S GUIDE

# **Appendix A. Schematic and Layouts**

#### A.1 INTRODUCTION

This appendix contains the following schematics and layouts for the EMC1833 Evaluation Board:

- ADM00773 Board Schematic
- ADM00773 Board Schematic 2
- Board Top Silk
- Board Top Copper and Silk
- Board Top Copper
- Board Bottom Copper
- Board Bottom Copper and Silk
- Board Bottom silk

### A.2 ADM00773 BOARD - SCHEMATIC



### A.3 ADM00773 BOARD – SCHEMATIC 2



#### **BOARD – TOP SILK** A.4 +3.3V +5V ALERT SCL CE J11 GND SDA GND J2 J3 **R8** R1 R2 Q1 , 7 EMC1833 9 C3 C2 MICROCHIP ] EMC1833 Customer Evaluation Board ADM00773

### A.5 BOARD – TOP COPPER AND SILK



### A.6 BOARD – TOP COPPER



### A.7 BOARD – BOTTOM COPPER





### A.9 BOARD – BOTTOM SILK





# EMC1833 EVALUATION BOARD USER'S GUIDE

# Appendix B. Bill of Materials (BOM)

TAB	ABLE B-1: BILL OF MATERIALS (BOM) FOR EMC1833 EVALUATION BOARD (ADM00773) <sup>(1)</sup>									
Qty.	Reference	Description	Manufacturer	Part Number						
4	C2, C6, C7, C18	Capacitor Ceramic, 0.1 µF, 100V, 10%, X7R, SMD, 0603	Murata Electronics North America, Inc.	GRM188R72A104KA35D						
1	C3	Capacitor Ceramic, 1000 pF, 50V, 20%, X7R, SMD, 0603	KEMET	C0603C102M5RACTU						
2	C4, C5	Capacitor Ceramic,10 µF, 10V, 10%, X5R, SMD, 0805	Taiyo Yuden Co., Ltd.	LMK212BJ106KD-T						
1	C19	Capacitor Ceramic, 10 µF, 10V, 10%, X5R, SMD, 0805	Taiyo Yuden Co., Ltd.	LMK212BJ106KG-T						
1	FB1	Ferrite, 2A, 220R, SMD, 0805	Murata Electronics North America, Inc.	BLM21PG221SN1D						
1	J2	Connector USB mini-B, Female, SMD, R/A	Hirose Electric Co., Ltd.	UX60-MB-5ST						
1	J3	Connector Term, Block, 5 MM 2-Position, GRN	PHOENIX CONTACT	1792863						
4	PAD1, PAD2, PAD3, PAD4	Mechanical HW Rubber PAD, Cylindrical, D7.9, H5.3, Black	3М	SJ61A11						
1	PCB1	Printed Circuit Board - EMC1833 Evalua- tion Board	Microchip Technology Inc.	04-10567-R2						
1	Q1	Transistor BJT, NPN, 40V, 200 mA, 310 mW, SOT-23-3	Fairchild Semiconductor <sup>®</sup>	MMBT3904						
4	R1, R2, R8, R21	Resistor TKF, 10k, 1%, 1/10W, SMD, 0402	Panasonic <sup>®</sup> - BSG	ERJ-2RKF1002X						
1	R4	Resistor TKF, 10k, 5%, 1/10W, SMD, 0603	Panasonic <sup>®</sup> - BSG	ERJ-3GEYJ103V						
1	R16	Resistor TKF, 100R, 1%, 1/10W, SMD, 0402	Panasonic <sup>®</sup> - BSG	ERJ-2RKF1000X						
1	TP1	Connector Test Point, Loop, Orange, TH	Keystone Electronics Corp.	5013						
2	TP2, TP7	Connector Test Point, Loop, Black, TH	Keystone Electronics Corp.	5011						
1	TP3	Connector Test Point, Loop, Red, TH	Keystone Electronics Corp.	5010						
3	TP4, TP5, TP6	Connector Test Point, Loop, White, TH	Keystone Electronics Corp.	5012						
1	U1	Microchip Analog LDO, 3.3V, SOT-223-3	Microchip Technology Inc.	MCP1825ST-3302E/DB						
1	U2	Microchip MCU, 8-bit, 48 MHz, 32 kB, 2 kB, QFN-28	Microchip Technology Inc.	PIC18LF25K50-I/ML						
1	U3	Three Channel 1.8V, I <sup>2</sup> C, Temperature Sensor	Microchip Technology Inc.	EMC1833T-AE/RW						
1	X1	DO NOT POPULATE	Murata Electronics North America, Inc.	CSTCE20M0V13L99-R0						

**Note 1:** The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.

# TABLE B-2:BILL OF MATERIALS (BOM) FOR EMC1833 EVALUATION BOARD (ADM00773) -<br/>MECHANICAL PARTS<sup>(1)</sup>

Qty.	Reference	Description	Manufacturer	Part Number
1	CBL1	Mechanical HW, cable USB-A Male to Mini USB-B Male, 3 ft, Black	Qualtek Electronics Corp.	3021003-03
1	Q2	Transistor, NPN, 40V, 0.2A, TO-92	Fairchild Semiconductor <sup>®</sup>	2N3904TA

**Note 1:** The components listed in this Bill of Materials are representative of the PCB assembly. The released BOM used in manufacturing uses all RoHS-compliant components.



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